



30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
30V	6mΩ @ V _{GS} = 10V	13A
307	10.5mΩ @ V _{GS} = 4.5V	10A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- · General purpose interfacing switches
- Power management functions

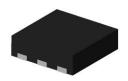
Features

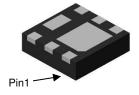
- 0.6mm Profile Ideal for Low-Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Low On-Resistance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

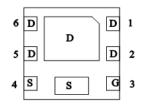
- Package: U-DFN2020-6
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish—NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.007 grams (Approximate)



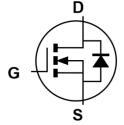




Top View Bottom View







Equivalent Circuit

Ordering Information (Note 4)

Part Number	Package	Packing		
Part Number	Раскауе	Qty.	Carrier	
DMT35M4LFDF-7	U-DFN2020-6 (Type F)	3,000	Tape & Reel	
DMT35M4LFDF-13	U-DFN2020-6 (Type F)	10,000	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



Marking Information

Site 1



XA = Product Type Marking Code YM = Date Code Marking Y = Year (ex: J = 2022)

M = Month (ex: 9 = September)

Date Code Kev

Date Code Ney												
Year	2019		2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	G		J	K	L	М	N	0	Р	R	S	T
	ı		ı	ı	ı			ı	ı	ı	ı	
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



XA = Product Type Marking Code YWX = Date Code Marking

Y = Year (ex: 2 = 2022)

W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2019	 2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	9	 2	3	4	5	6	7	8	9	0	1

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Υ	Z



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	30	V		
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current Vos. 10V (Note C)	Steady	T _A = +25°C	la.	13	^
Continuous Drain Current, V _{GS} = 10V (Note 6)	State	T _A = +70°C	ID	11	^
Maximum Body Diode Forward Current			Is	2.4	Α
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%	(6)		Ірм	90	Α
Pulsed Drain Body Diode Forward Current (380µs P	= 1%)	lsм	90	Α	
Avalanche Current (L = 0.1mH) (Note 8)	I _{AS}	22	Α		
Avalanche Energy (L = 0.1mH) (Note 8)			Eas	25	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.86	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	147	°C/W
Total Power Dissipation (Note 6)		PD	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	73	°C/W
Thermal Resistance, Junction to Case (Note 7)		R _θ JC	6.7	°C/ VV
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BVDSS	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μΑ	$V_{DS} = 24V, V_{GS} = 0V$
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	V _{GS(TH)}	1.15	_	2.5	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$
Static Drain-Source On-Resistance	Dag (a) ii		4.9	6	mΩ	$V_{GS} = 10V, I_{D} = 20A$
Static Diani-Source On-Nesistance	R _{DS(ON)}	_	7.1	10.5	11122	$V_{GS} = 4.5V, I_D = 15A$
Diode Forward Voltage	VsD	_	0.7	1	V	$V_{GS} = 0V$, $I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	Ciss	_	1009	_		V 45V V 0V
Output Capacitance	Coss	_	925	_	рF	V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	50	_		1 – 1.01011 12
Gate Resistance	Rg	_	2	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1.0MHz$
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	8.1	_		
Total Gate Charge (V _{GS} = 10V)	Qg	_	14.9	_	nC	V _{DD} = 15V. I _D = 9A
Gate-Source Charge	Qgs		2.3	_	ПС	VDD = 15V, ID = 9A
Gate-Drain Charge	Q_{gd}	_	3.4	_		
Turn-On Delay Time	td(ON)		3.6	_		
Turn-On Rise Time	t _R	_	4.4	_	ns	$V_{DD} = 15V, V_{GS} = 10V,$
Turn-Off Delay Time	t _{D(OFF)}	_	15	_	115	$R_g=3\Omega,\ I_D=9A$
Turn-Off Fall Time	tF	_	6.9	_		
Reverse Recovery Time	trr	_	29.4	_	ns	I_ 1 5A di/dt 100A/uc
Reverse Recovery Charge	Qrr	_	19.2	_	nC	I _F = 1.5A, di/dt = 100A/μs

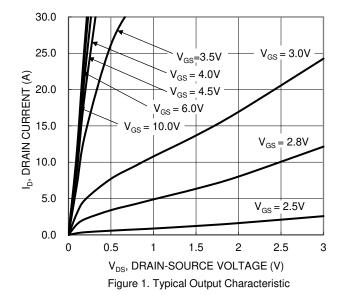
5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

- Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 Thermal resistance from junction to soldering point (on the exposed drain pad).
 I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.

- 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.







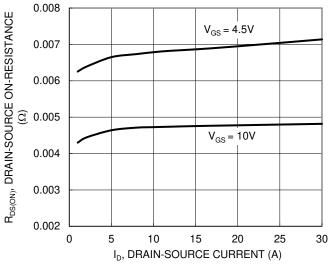
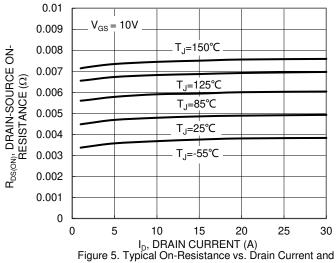
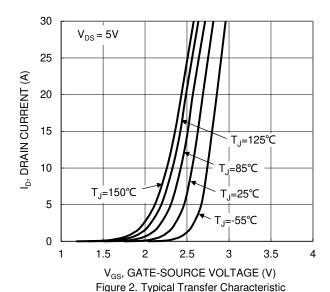
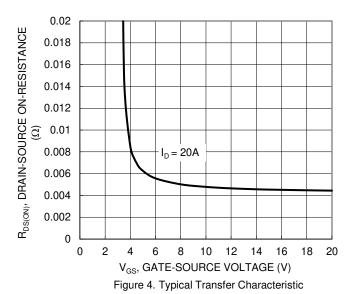


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage



Junction Temperature





R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED) 1.6 $V_{GS} = 10V, I_D = 20A$ 1.2 1 $V_{GS} = 4.5V, I_D = 15A$ 8.0

T_J, JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Junction Temperature

50

1.8

0.6

-50

-25

0

25

75

125

150

100





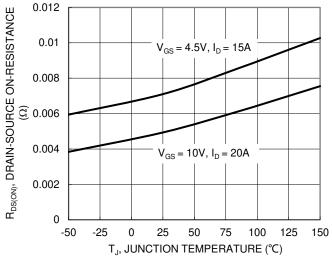
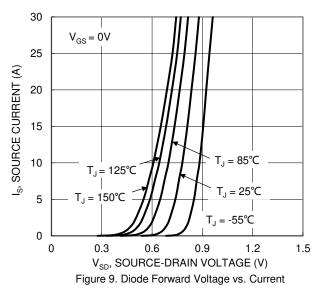


Figure 7. On-Resistance Variation with Junction Temperature



6 V_{DS} = 15V, I_D = 9A 2 0 0 3 6 9 12 15

Qg (nC) Figure 11. Gate Charge

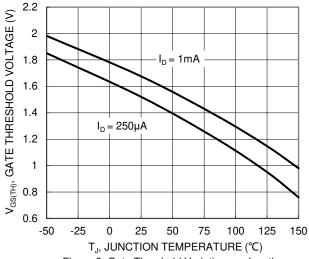
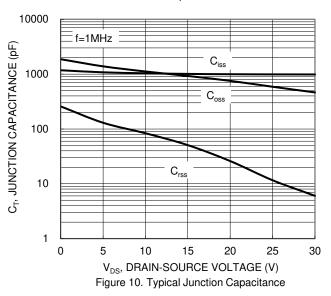


Figure 8. Gate Threshold Variation vs. Junction Temperature



100 R_{DS(ON)} Limited 10 ID, DRAIN CURRENT (A) 1 =1ms =10ms =100ms 0.1 $T_{J(Max)} = 150\,^{\circ}\mathrm{C}$ $T_{C} = 25\,^{\circ}\mathrm{C}$ 0.01 Single Pulse DUT on 1*MRP Board $V_{GS} = 10V$ 0.001 10 0.01 100 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area

10

8



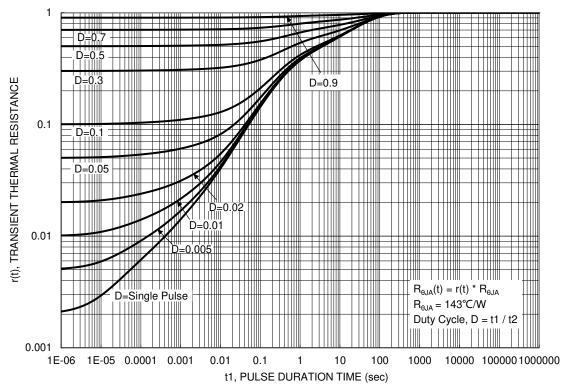


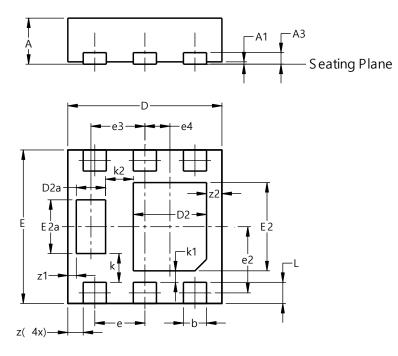
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

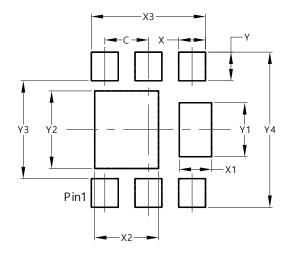


	U-DFN2020-6							
		oe F)						
Dim	Min	Max	Тур					
Α	0.57	0.63	0.60					
A 1	0.00	0.05	0.03					
А3	-	-	0.15					
b	0.25	0.35	0.30					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
D2a	0.33	0.43	0.38					
Е	1.95	2.05	2.00					
E2	1.05	1.25	1.15					
E2a	0.65	0.75	0.70					
е		0.65 BS	C					
e2	C).863 BS	SC					
e3	(0.70 BS	C					
e4	C	.325 BS	SC					
k	(0.37 BS	C					
k1	(0.15 BS	C					
k2	(0.36 BS	C					
L	0.225 0.325 0.275							
Z	0.20 BSC							
z1	C).110 BS	SC					
z2		0.20 BS	С					
All D	imens	ions in	mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
С	0.650
Х	0.400
X1	0.480
X2	0.950
Х3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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